

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A focus ring assembly configured to reduce process effects on the backside of a substrate that is cantilevered beyond an edge of a substrate holder support surface on which the substrate rests, the focus ring assembly[[,]] comprising:

a focus ring ~~including~~ positioned on a step receiving surface, ~~the focus ring being positioned on a~~ of the substrate holder which is axially recessed from the substrate holder support surface and extends radially outward from the edge of the substrate holder support surface, the focus ring comprising:

a bottom surface which contacts the step receiving surface of the substrate holder,

a top surface which opposes the bottom surface and is axially positioned at a higher level than the substrate support surface when the focus ring is positioned on the step receiving surface of the substrate holder, and

a lip having a lip receiving surface axially located between the bottom surface and top surface of the focus ring, such that the lip receiving surface is [[and]] located below a backside surface of a substrate resting on the substrate support surface of the substrate holder, and an outer radial lip surface positioned radially outward from a peripheral edge of the substrate and extending upward from the lip receiving surface to the top surface of the focus ring such that a clearance space is formed between a cantilevered portion of the substrate and the lip of the focus ring; and

a secondary focus ring positioned on the ~~step~~ lip receiving surface of the focus ring, the secondary focus ring including an inner radial edge surface extending axially upward

from the lip receiving surface and positioned radially outward from the peripheral edge of the substrate,

wherein said focus ring is configured to couple to the substrate holder which is configured to support the substrate exposed to a process in a processing system, and said secondary focus ring is configured to reduce deposition of material from said process on the backside surface of said substrate.

Claim 2 (Previously Presented): The focus ring assembly as recited in claim 1, wherein said secondary focus ring comprises a compliant material.

Claim 3 (Previously Presented): The focus ring assembly as recited in claim 2, wherein said compliant material comprises at least one of silicone rubber, polyimide, and Teflon.

Claim 4 (Previously Presented): The focus ring assembly as recited in claim 1, wherein said secondary focus ring comprises a rigid material.

Claim 5 (Previously Presented): The focus ring assembly as recited in claim 4, wherein said rigid material comprises at least one of a ceramic material, silicon, silicon carbide, silicon nitride, silicon dioxide, carbon, sapphire, and alumina.

Claim 6 (Previously Presented): The focus ring assembly as recited in claim 1, wherein said secondary focus ring comprises silicon having a resistivity less than or equal to  $1\ \Omega\text{-cm}$ .

Claim 7 (Currently Amended): The focus ring assembly as recited in claim 1, wherein ~~[[a]] the clearance space is formed between said substrate and said focus ring, and said clearance space~~ exposes at least a portion of said backside surface on said substrate and said secondary focus ring reduces said clearance space.

Claim 8 (Previously Presented): The focus ring assembly as recited in claim 7, wherein said secondary focus ring reduces exposure of said backside surface.

Claim 9 (Previously Presented): The focus ring assembly as recited in claim 1, wherein a portion of said backside surface on said substrate is exposed and wherein said secondary focus ring reduces said exposure of said backside surface.

Claims 10-20. (Canceled).

Claim 21 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the outer radial lip surface of the focus ring is positioned radially outward from an outer radial edge surface of the secondary focus ring.

Claim 22 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the outer radial lip surface of the focus ring is positioned radially outward from and in contact with an outer radial edge surface of the secondary focus ring.

Claim 23 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the secondary focus ring has an annular shape and a cross-section of the secondary focus ring has a rectangular shape.

Claim 24 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the focus ring has an annular shape and a cross-section of the secondary focus ring has an L-shape.

Claim 25 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the secondary focus ring is positioned entirely radially outward from the substrate.

Claim 26 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the secondary focus ring includes an upper surface that is substantially planar with a top surface of the substrate.

Claim 27 (Previously Presented): The focus ring assembly as recited in claim 26, wherein the focus ring includes an upper surface that is substantially planar with the upper surface of the secondary focus ring and the top surface of the substrate.

Claim 28 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the entire secondary focus ring is positioned radially inside of the outer radial lip surface of the focus ring.

Claim 29 (Previously Presented): The focus ring assembly as recited in claim 1, wherein the focus ring extends further radially inward than the secondary focus ring.

Claim 30 (Previously Presented/Withdrawn): A processing apparatus, comprising:  
a substrate holder;

a substrate positioned on the substrate holder; and  
focus ring assembly coupled to the substrate holder, the focus ring assembly  
comprising:

a focus ring including a step receiving surface, the focus ring being positioned  
on the substrate holder and located below a backside surface of the substrate, and an  
outer radial lip surface positioned radially outward from a peripheral edge of the  
substrate, and

a secondary focus ring positioned on the step receiving surface of the focus  
ring, the secondary focus ring including an inner radial edge surface positioned  
radially outward from the peripheral edge of the substrate such that a clearance space  
exists between the peripheral edge of the substrate and the inner radial edge surface of  
the secondary focus ring.

Claim 31 (Previously Presented/Withdrawn): The apparatus as recited in claim 30,  
wherein the substrate is positioned on the substrate holder such that a cantilevered outer  
portion of the substrate extends radially outward past an outer edge of the substrate holder.